Product Change Notification / BLAS-28XZGK309

Date:

01-Feb-2024

Product Category:

8-Bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 6736 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material for selected ATMEGA1608, ATmega168PB, ATMEGA3208, ATmega328PB, ATMEGA4808, ATmega48PB, ATMEGA808, ATmega88PB and AVR16EB32 device families available in 32L VQFN (5x5x0.9mm) package at MP3A assembly site.

Affected CPNs:

BLAS-28XZGK309_Affected_CPN_02012024.pdf
BLAS-28XZGK309_Affected_CPN_02012024.csv

Notification Text:

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material for selected ATMEGA1608, ATmega168PB, ATMEGA3208, ATmega328PB, ATMEGA4808, ATmega48PB, ATMEGA808, ATmega88PB and AVR16EB32 device families available in 32L VQFN (5x5x0.9mm) package at MP3A assembly site.

Pre and Post Change Summary:

	Pre Change	**Post Change**	
Assembly Site	Microchip Technology Inc. (MPHIL-3) (MP3A)	Microchip Technology Inc. (MPHIL-3) (MP3A)	Microchip Technology Inc. (MPHIL-3) (MP3A)
Wire Material	Au	Au	CuPdAu
Die Attach Material	3280	3280	3280
Molding Compound Material	G700LTD	G700LTD	G700LTD
Lead-Frame Material	C194	C194	C194

Impacts to Data Sheet: None

Change Impact: None

Reason for Change: To improve productivity and on-time delivery performance by qualifying palladium coated copper with gold flash (CuPdAu) as an additional bond wire material at MP3A assembly site.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: February 2024

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	February 2024				
Workweek	05	06	07	08	09
Initial PCN Issue Date	x				
Qual Report Availability					x
Final PCN Issue					x

Date					

Method to Identify Change: Traceability code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: February 01, 2024: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_BLAS-28XZGK309 Qual Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to change your PCN profile, including opt out, please go to the PCN home page select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

ATMEGA1608-MUR
ATMEGA1608-MF
ATMEGA1608-MFR
ATMEGA1608-MU
ATMEGA3208-MF
ATMEGA3208-MFR
ATMEGA3208-MU
ATMEGA3208-MUR
ATMEGA808-MF
ATMEGA808-MU
ATMEGA808-MUR
ATMEGA808-MFR
ATMEGA4808-MF
ATMEGA4808-MUR
ATMEGA4808-MU
ATMEGA168PB-MU
ATMEGA168PB-MN
ATMEGA168PB-MNR
ATMEGA168PB-MUR
ATMEGA88PB-MU
ATMEGA48PB-MU
ATMEGA88PB-MN
ATMEGA48PB-MN
ATMEGA88PB-MNR
ATMEGA48PB-MNR
ATMEGA88PB-MUR
ATMEGA48PB-MUR
ATMEGA328PB-MU
ATMEGA328PB-MN
ATMEGA328PB-MNR
ATMEGA328PB-MUR
ATMEGA4808-MFR
AVR16EB32-E/RXB
AVR16EB32-I/RXB
AVR16EB32T-I/RXB
AVR16EB32T-E/RXB